

N AMER PHILIPS/DISCRETE

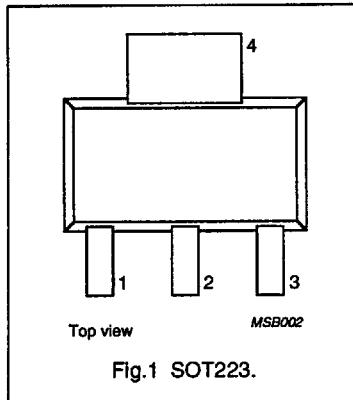
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FEATURES

- Low distortion
- Gold metallization ensures excellent reliability
- SOT223 plastic envelope
- High output voltage
- Integrated emitter-ballasting resistors

PINNING

PIN	DESCRIPTION
1	emitter
2	base
3	emitter
4	collector

**DESCRIPTION**

The BFG741 is an NPN silicon planar epitaxial transistor, primarily intended for use as a power amplifier in RF communications subscriber equipment and MATV/CATV amplifiers.

The transistor is mounted in a plastic SOT223 envelope.

Fig.1 SOT223.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	—	—	25	V
V_{CEO}	collector-emitter voltage	open base	—	—	15	V
I_C	DC collector current		—	—	300	mA
P_{tot}	total power dissipation	up to $T_s = 125^\circ\text{C}$ (note 1)	—	—	2	W
C_{re}	feedback capacitance	$I_C = i_c = 0$; $V_{CE} = 10$ V; $f = 1$ MHz	—	1.8	—	pF
h_{FE}	DC current gain	$V_{CE} = 10$ V; $I_C = 100$ mA	60	—	—	
f_T	transition frequency	$V_{CE} = 10$ V; $I_C = 200$ mA; $f = 500$ MHz	—	7	—	GHz
G_{UM}	maximum unilateral power gain	$V_{CE} = 10$ V; $I_C = 130$ mA; $T_{amb} = 25^\circ\text{C}$; $f = 800$ MHz	—	13	—	dB
V_o	output voltage	$V_{CE} = 10$ V; $I_C = 130$ mA; $R_L = 75 \Omega$ (note 2)	—	1	—	V
d_2	second order intermodulation distortion	$V_{CE} = 10$ V; $I_C = 130$ mA; $T_{amb} = 25^\circ\text{C}$; $V_o = 54$ dBmV (0.5 V); $f_{(p+q)} = 810$ MHz	—	-60	—	dB
T_j	junction temperature		—	—	175	°C

THERMAL RESISTANCE

SYMBOL	PARAMETER	THERMAL RESISTANCE
$R_{th J-s}$	from junction to soldering point (note 1)	25 K/W

Notes

1. T_s is the temperature at the soldering point of the collector tab.
2. $d_{im} = -60$ dB (3-tone); $V_p = V_o$; $V_q = V_r = V_o - 6$ dB; $f_p = 795.25$ MHz; $f_q = 803.25$ MHz; $f_r = 805.25$ MHz; measured at $f_{(p+q+r)} = 793.25$ MHz.